

ABSTRACT

FLEXIBLE BALL GRID ARRAY CHIP SCALE PACKAGES
AND METHODS OF FABRICATION

A method and apparatus for increasing the integrated circuit density in a semiconductor assembly. The assembly includes a flexible interposer substrate attached to an active surface and a back side of a first die, the interposer substrate wrapping
5 around at least one side of the first die. The assembly also includes an array of discrete conductive elements connected to bond pads of the first die through conductive traces and exposed on an exterior surface of the interposer substrate for effecting an external electrical connection. The assembly may include a second die facing the first die and attached to the interposer substrate, the interposer substrate being wrapped around
10 either the first or second die or, alternatively, being wrapped around both the first and second die. Designate Figure 1(g).